

1241891-3 ✓ ACTIVE

AMPMODU

TE Internal #: 1241891-3

PCB Mount Header, Right Angle, Board-to-Board, 3 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, Black

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Right Angle**

Connector System: **Board-to-Board**

Number of Positions: **3**

Number of Rows: **1**

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Breakaway
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

PCB Mount Orientation	Right Angle
Number of Positions	3
Number of Rows	1
Board-to-Board Configuration	Perpendicular

Body Features

Primary Product Color	Black
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Contact Features

Contact Mating Area Plating Material	Gold
Contact Type	Pin
Contact Current Rating (Max)	3 A

Termination Features

Termination Method to Printed Circuit Board	Through Hole - Solder
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Mechanical Attachment

Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount

Housing Features

Centerline (Pitch)	2.54 mm [.1 in]
Housing Material	PCT GV

Dimensions

PCB Thickness (Recommended)	1.57 mm [.062 in]
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Usage Conditions

Operating Temperature Range	-65 – 105 °C [-85 – 221 °F]
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Operation/Application

Circuit Application	Signal
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Type	Box, Carton
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Documents

Product Drawings

MOD2 ST-LEIS90 3P

English

CAD Files

Customer View Model

ENG_CVM_1241891-3_A2.3d_igs.zip

English

Customer View Model

ENG_CVM_1241891-3_A2.3d_stp.zip

English

Customer View Model

ENG_CVM_1241891-3_A2.2d_dxf.zip

English

3D PDF

3D

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

AMPMODU Interconnection System

AMPMODU Interconnection System

English